

Parker Chomerics CHO-BOND 1086 Conductive Caulk/Sealant

Category : Polymer , Adhesive , Thermoset

Material Notes:

Chomerics two-component conductive epoxy caulks provide excellent adhesion to dissimilar substrates and can be used in lap or butt joint applications. They feature large silver-plated-copper particles that make them well suited for sealing poorly tolerated surfaces. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-1086-Conductive-CaulkSealant.php

Physical Properties	Metric	English	Comments
Specific Gravity	0.680 - 0.880 g/cc	0.680 - 0.880 g/cc	
Volatile Organic Compounds (VOC) Content	740 g/l	740 g/l	
Thickness	<= 5.08 microns	<= 0.200 mil	

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	200 °C	392 °F	
Minimum Service Temperature, Air	-20.0 °C	-4.00 °F	

Processing Properties	Metric	English	Comments
Cure Time	30.0 min @Temperature 23.0 °C	0.500 hour @Temperature 73.4 °F	
Shelf Life	6.00 Month	6.00 Month	

Descriptive Properties	Value	Comments
Binder	Primer	
Consistency	Thin Fluid	
Mix Ratio	1-part	

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